

RFM25N05, RFM25N06, RFP25N05, RFP25N06

File Number 1492

Power MOS Field-Effect Transistors

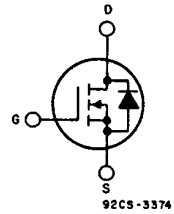
N-Channel Enhancement-Mode Power Field-Effect Transistors

25 A, 50 V - 60 V  
 $r_{DS(on)} = 0.07\Omega$

Features:

- SOA is power-dissipation limited
- Nanosecond switching speeds
- Linear transfer characteristics
- High input impedance
- Majority carrier device

TERMINAL DIAGRAM



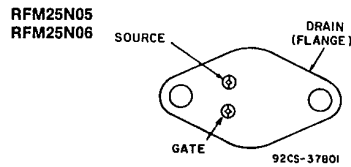
N-CHANNEL ENHANCEMENT MODE

The RFM25N05 and RFM25N06 and the RFP25N05 and RFP25N06\* are n-channel enhancement-mode silicon-gate power field-effect transistors designed for applications such as switching regulators, switching converters, motor drivers, relay drivers, and drivers for high-power bipolar switching transistors requiring high speed and low gate-drive power. These types can be operated directly from integrated circuits.

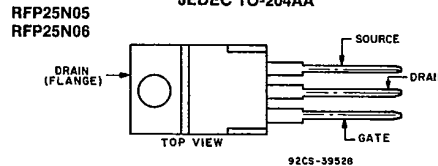
The RFM-types are supplied in the JEDEC TO-204AA steel package and the RFP-types in the JEDEC TO-220AB plastic package.

\*The RFM and RFP series were formerly RCA developmental numbers TA9386 and TA9387, respectively.

TERMINAL DESIGNATIONS



JEDEC TO-204AA



JEDEC TO-220AB

MAXIMUM RATINGS, Absolute-Maximum Values ( $T_C=25^\circ C$ ):

	RFM25N05	RFM25N06	RFP25N05	RFP25N06	
DRAIN-SOURCE VOLTAGE ..... $V_{DS}$	50	60	50	60	V
DRAIN-GATE VOLTAGE ( $R_{gs}=1 M\Omega$ ) .... $V_{DGR}$	50	60	50	60	V
GATE-SOURCE VOLTAGE ..... $V_{GS}$	± 20		± 20		V
DRAIN CURRENT, RMS Continuous ..... $I_D$	25		25		A
Pulsed ..... $I_{DM}$	60		60		A
POWER DISSIPATION @ $T_C$ 25°C ..... $P_T$	100	100	75	75	W
Derate above $T_C$ 25°C	0.8	0.8	0.6	0.6	W/°C
OPERATING AND STORAGE TEMPERATURE ..... $T_r, T_{stg}$	-55 to +150		-55 to +150		°C

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**ELECTRICAL CHARACTERISTICS, At Case Temperature (T<sub>c</sub>)=25° C unless otherwise specified.**

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	LIMITS				UNITS
			RFM25N05 RFP25N05		RFM25N06 RFP25N06		
			MIN.	MAX.	MIN.	MAX.	
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	I <sub>D</sub> =1 mA V <sub>GS</sub> =0	50	—	60	—	V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>GS</sub> =V <sub>DS</sub> I <sub>D</sub> =1 mA	2	4	2	4	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =40 V V <sub>GS</sub> =50 V	—	1	—	—	μA
		T <sub>c</sub> =125° C V <sub>DS</sub> =40 V V <sub>GS</sub> =50 V	—	50	—	50	
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20 V V <sub>DS</sub> =0	—	100	—	100	nA
Drain-Source On Voltage	V <sub>DS(on)</sub> <sup>a</sup>	I <sub>D</sub> =12.5 A V <sub>GS</sub> =10 V	—	1.06	—	1.06	V
		I <sub>D</sub> =25 A V <sub>GS</sub> =10 V	—	2.5	—	2.5	
Static Drain-Source On Resistance	r <sub>DS(on)</sub> <sup>a</sup>	I <sub>D</sub> =12.5 A V <sub>GS</sub> =10 V	—	0.07	—	0.07	Ω
Forward Transconductance	g <sub>fs</sub> <sup>a</sup>	V <sub>DS</sub> =10 V I <sub>D</sub> =12.5 A	5	—	5	—	mho
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25 V	—	1700	—	1700	pF
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> =0 V	—	900	—	900	
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1MHz	—	400	—	400	
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =30 V I <sub>D</sub> =12.5 A	18(typ)	60	18(typ)	60	ns
Rise Time	t <sub>r</sub>	R <sub>gen</sub> =R <sub>gs</sub> =50 Ω	120(typ)	225	120(typ)	225	
Turn-Off Delay Time	t <sub>d(off)</sub>	V <sub>GS</sub> =10 V	123(typ)	225	123(typ)	225	
Fall Time	t <sub>f</sub>		123(typ)	200	123(typ)	200	
Thermal Resistance Junction-to-Case	R <sub>θJC</sub>	RFM25N05, RFM25N06	—	1.25	—	1.25	°C/W
		RFP25N05, RFP25N06	—	1.67	—	1.67	

<sup>a</sup>Pulsed: Pulse duration = 300 μs max., duty cycle = 2%.

**SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS**

CHARACTERISTIC	SYMBOL	TEST CONDITIONS	LIMITS				UNITS
			RFM25N05 RFP25N05		RFM25N06 RFP25N06		
			MIN.	MAX.	MIN.	MAX.	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>SD</sub> =12.5 A	—	1.4	—	1.4	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> =4 A d <sub>IF</sub> /d <sub>I</sub> =100 A/μs	150(typ)		150(typ)		ns

\*Pulse Test: Width ≤ 300 μs, duty cycle ≤ 2%.

RFM25N05, RFM25N06, RFP25N05, RFP25N06

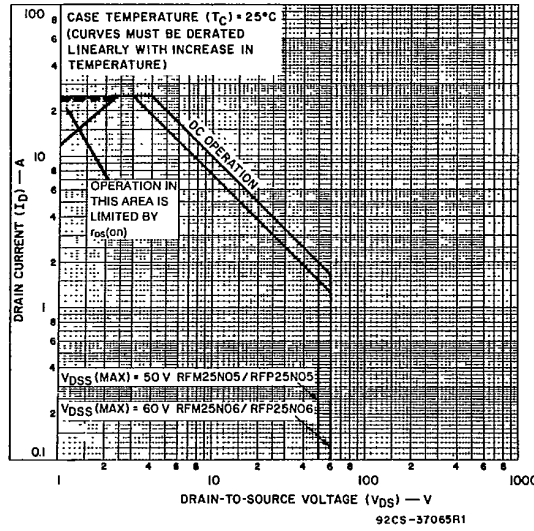


Fig. 1 — Maximum operating areas for all types.

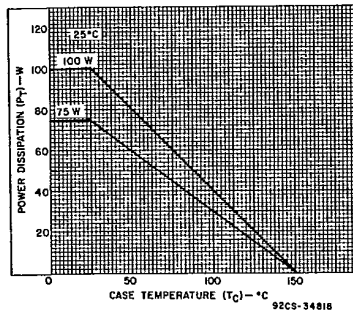


Fig. 2 — Power dissipation vs. case temperature derating curve for all types.

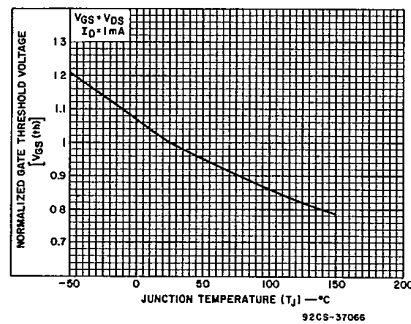


Fig. 3 — Typical normalized gate threshold voltage as a function of junction temperature for all types.

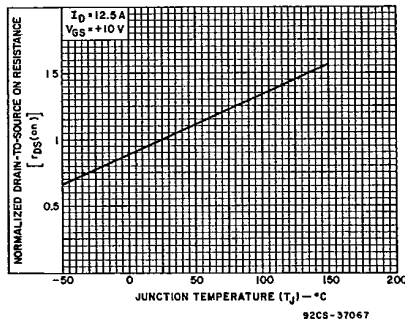


Fig. 4 — Normalized drain-to-source on resistance to junction temperature for all types.

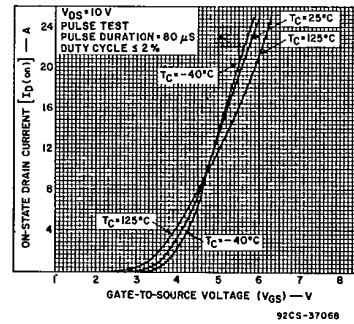


Fig. 5 — Typical transfer characteristics for all types.

RFM25N05, RFM25N06, RFP25N05, RFP25N06

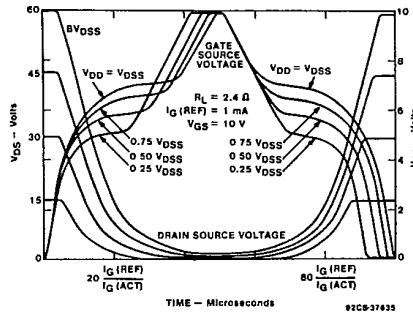


Fig. 6 - Normalized switching waveforms for constant gate-current drive.

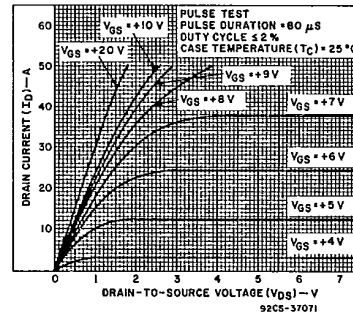


Fig. 7 - Typical saturation characteristics for all types.

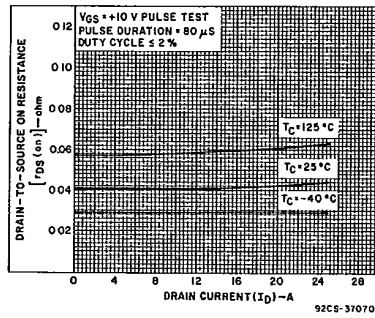


Fig. 8 - Typical drain-to-source on resistance as a function of drain current for all types.

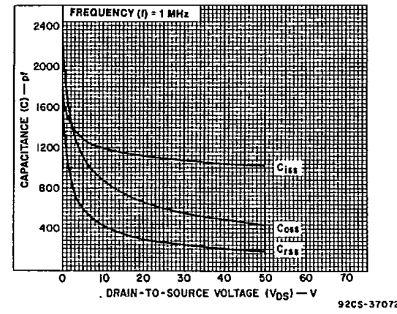


Fig. 9 - Capacitance as a function of drain-to-source voltage for all types.

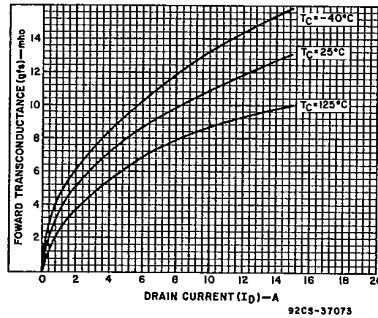


Fig. 10 - Typical forward transconductance as a function of drain current for all types.

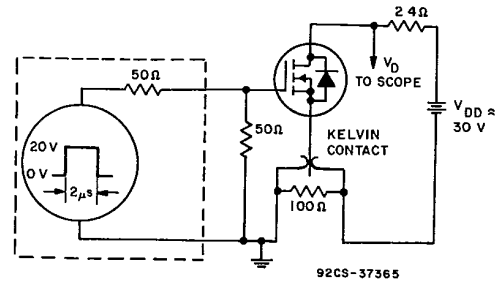


Fig. 11 - Switching Time Test Circuit